ABSTRACT OF THE DISCLOSURE

A method and system of manufacturing an air bag cover assembly utilizing infrared radiation is disclosed. The assembly includes a front panel, a back plate, a switch and infrared-absorbing material. Initially, the front panel and the back plate are positioned so that inner surfaces of the front panel and the back plate define a switch pocket therebetween. Then the switch is positioned in the switch pocket. Thereafter, infrared radiation is directed at the infrared-absorbing material for a time sufficient to heat the infrared-absorbing material to a desired temperature. The amount of heat applied to the infrared-absorbing material by the infrared radiation is controlled by a controller. Finally, the heated material cools to fixedly secures the back plate to the front panel. The heated material may be forced to flow prior to cooling. In one embodiment, the back plate includes a plurality of spaced holes extending therethrough and wherein the infrared-absorbing material forms a plurality of stakes connected to the inner surface of the front panel and extending through the plurality of spaced holes. The heated infrared-absorbing material forms a plurality of solid connectors after cooling. In another embodiment, the infrared-absorbing material is a heat-activated adhesive and the method further includes applying the heat-activated adhesive to at least one of the inner surfaces of the front panel and the back plate.